Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.011”**

**ANODE**

**.011”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size: .0035” X .0035”**

**Backside Potential: CATHODE**

**Mask Ref: CPD83V**

**APPROVED BY: DK DIE SIZE .011” X .011” DATE: 8/26/21**

**MFG: CENTRAL SEMI THICKNESS .007” P/N: 1N4454**

**DG 10.1.2**

#### Rev B, 7/1